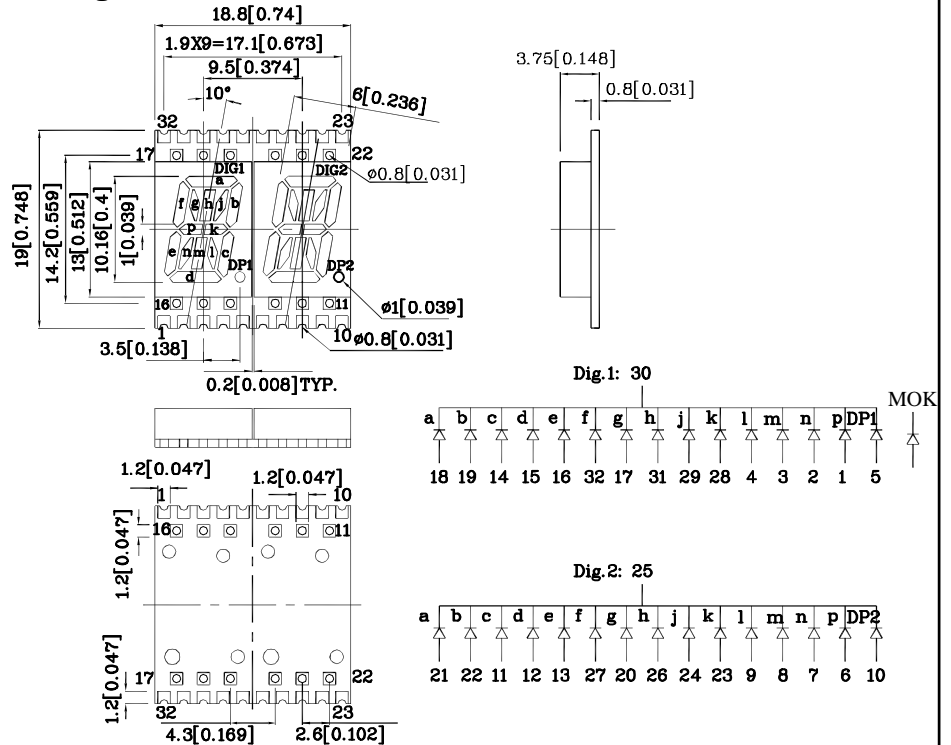


**Features**

- 0.4 inch digit height
- Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 250pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS Compliant



**Package Schematics**



**Notes:**

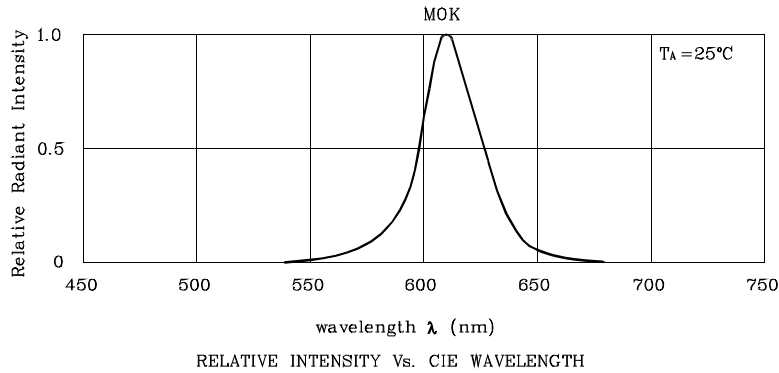
1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. Specifications are subject to change without notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm.

Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )		MOK (AlGaInP)	Unit
Reverse Voltage	$V_R$	5	V
Forward Current	$I_F$	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{FS}$	195	mA
Power Dissipation	$P_D$	75	mW
Operating Temperature	$T_A$	-40 ~ +85	°C
Storage Temperature	$T_{stg}$	-40 ~ +85	

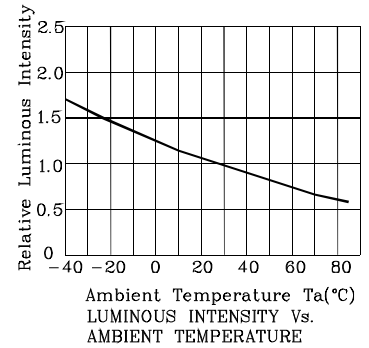
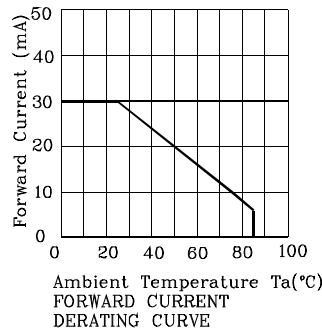
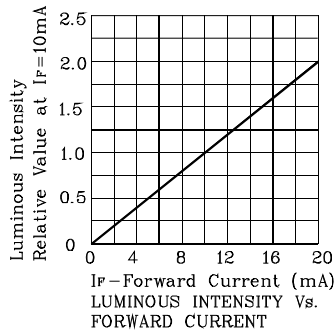
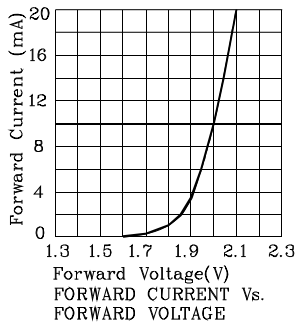
Operating Characteristics ( $T_A=25^\circ\text{C}$ )		MOK (AlGaInP)	Unit
Forward Voltage (Typ.) ( $I_F=10\text{mA}$ )	$V_F$	2	V
Forward Voltage (Max.) ( $I_F=10\text{mA}$ )	$V_F$	2.5	V
Reverse Current (Max.) ( $V_R=5\text{V}$ )	$I_R$	10	$\mu\text{A}$
Wavelength of Peak Emission CIE127-2007* (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_P$	610*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_D$	601*	nm
Spectral Line Full Width At Half-Maximum (Typ.) ( $I_F=10\text{mA}$ )	$\Delta\lambda$	29	nm
Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )	C	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* ( $I_F=10\text{mA}$ ) ucd		Wavelength CIE127-2007* nm $\lambda_P$	Description
			min.	typ.		
XZFAMOK10C2	Orange	AlGaInP	21000 5600*	43990 12990*	610*	Common Cathode, Rt. Hand Decimal

\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ MOK



**LED is recommended for reflow soldering and soldering profile is shown below.**

**Reflow Soldering Profile for SMD Products (Pb-Free Components)**

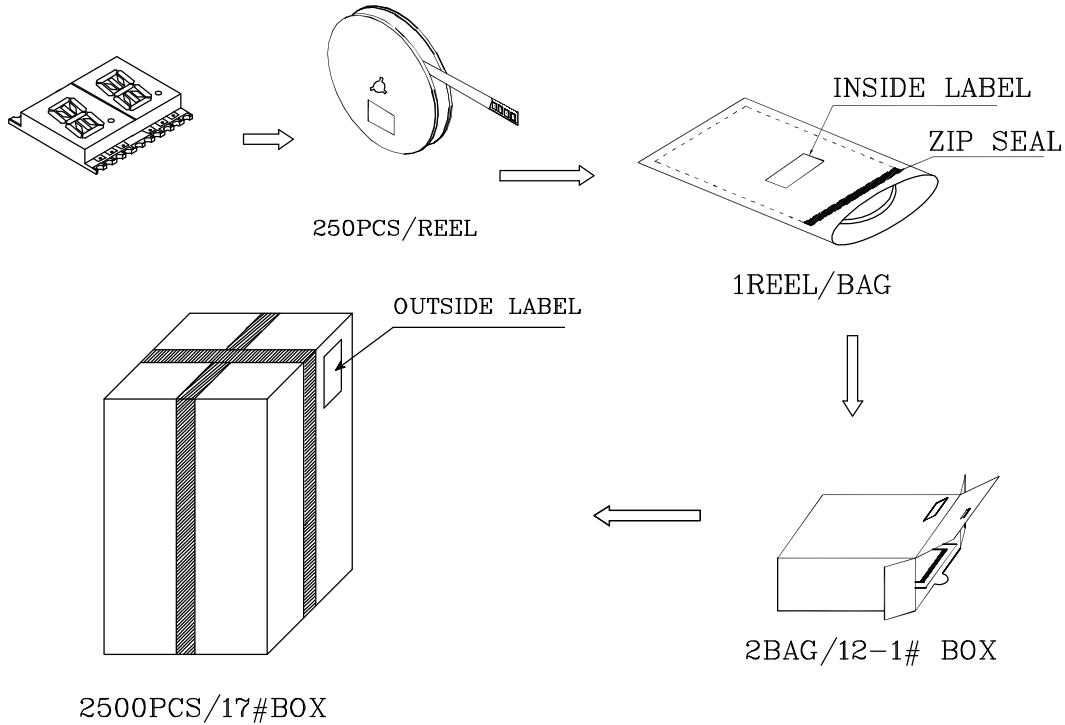


**Notes:**

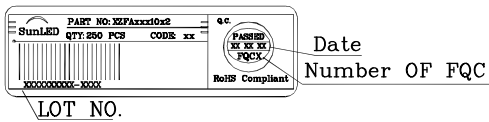
1. Maximum soldering temperature should not exceed 260°C
2. Recommended reflow temperature: 145°C-260°C
3. Do not put stress to the epoxy resin during high temperatures conditions



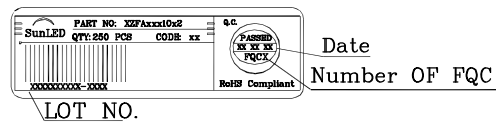
PACKING & LABEL SPECIFICATIONS



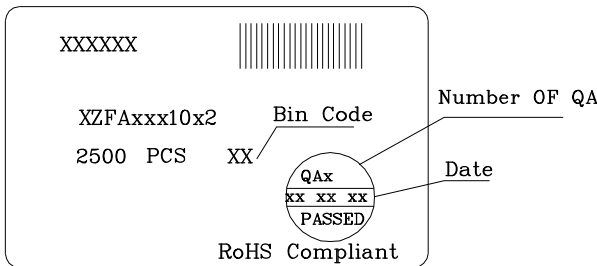
Inside LABEL On Tape



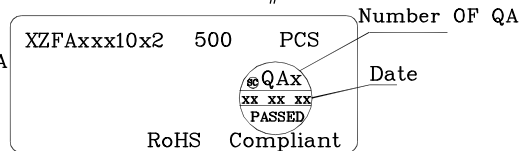
Outside LABEL On BAG



Outside LABEL On 19#Box



Outside LABEL On 12#Box



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4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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